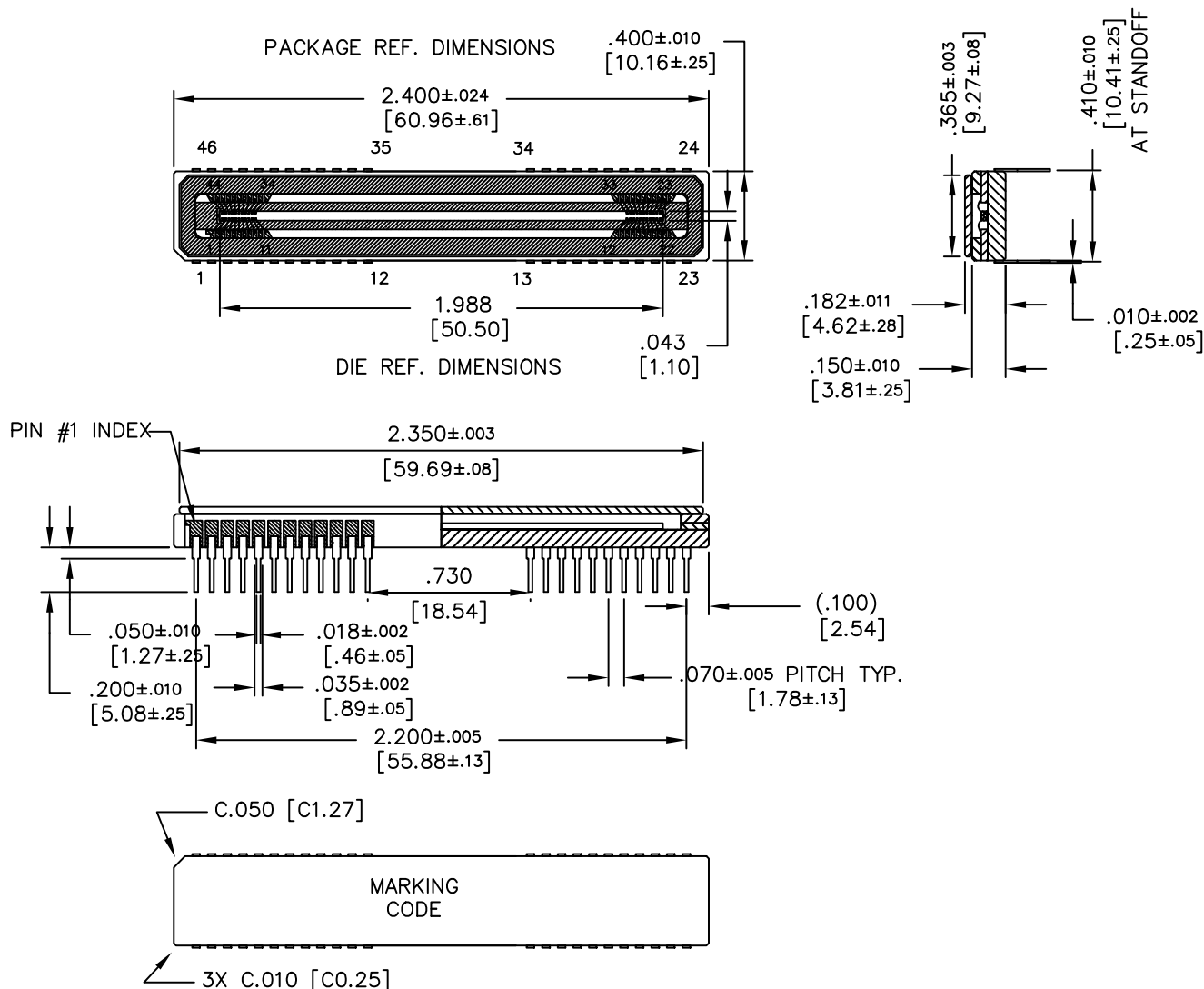


**CERAMIC DIP 46, 60.96x10.16**  
CASE 125BP  
ISSUE O

DATE 03 JUL 2014



NOTES:

1. LEADS 1 AND 23 ATTACHED TO DIE ATTACH METALLIZATION.
2. LEADS 12 AND 35 ARE NOT CONNECTED.
3. MATERIALS: PINS=ALLOY 42, CERAMIC=BLACK ALUMINA.
4. COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER PACKAGE - LOCATION ACCURACY IS NOT GUARANTEED.

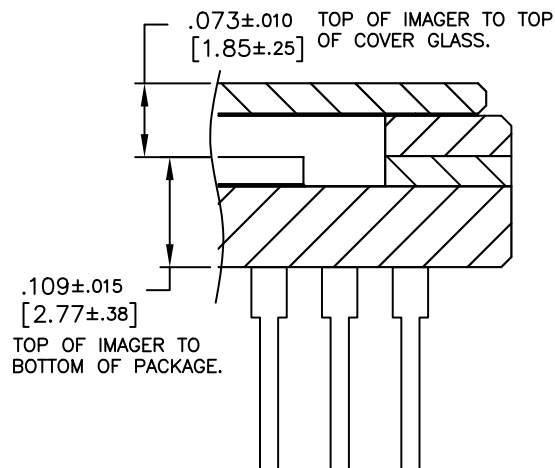
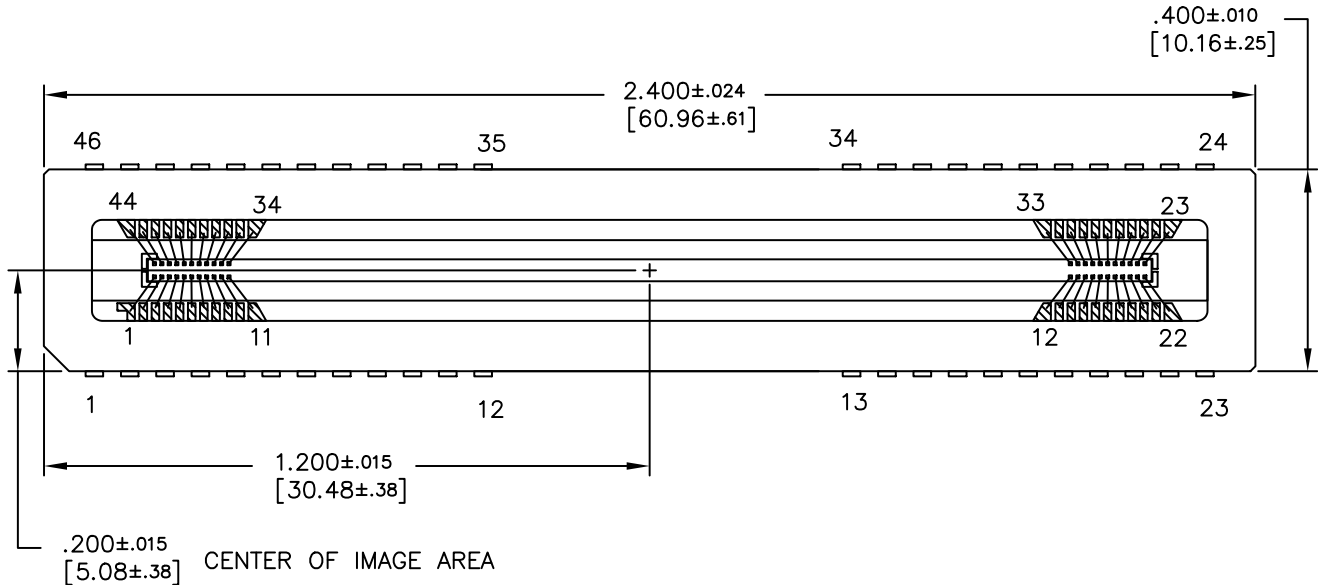
**Dimensions in: Inches [mm]**

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**NOTES:**

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.00,0.00)mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN  $\pm 0.75$  DEGREE OF ANY PACKAGE CAVITY EDGE.

**Dimensions in: Inches [mm]**

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